

RECOMMENDED P.C.B LAYOUT  
(TOLERANCE:±0.05)

發行  
103. 5. 14  
文管中心


REV	MODIFICATION	DATE	DRAW
A0	Release To Production	2014.05.14	Michelle

Specification  
 1.Current Rating:3A AC/DC(Max) AWG#22  
 2.Voltage Rating:250V AC/DC  
 3.Contact Resistance:20mΩ Max.  
 4.Insulation Resistance:1000MΩ Min.  
 5.Withstand Voltage:AC800V/Minute  
 6.Operating Temperature:-25°C~+85°C

Material:  
 1.Housing:High Temperature Thermoplastic UL94V-0  
 2.Tab:Copper Alloy T=0.40mm  
 3.Contact Pin:Copper Alloy SQ. Pin 0.50mm  
 Finish:  
 1.Housing:Nature  
 2.Tab:Bright Tin Plated Over Nickel  
 3.Contact Pin: See P/N Option


Part No.: AS06401 XX 5 X X 2  
 Number of Pin 02~15      Packing 1:T&R 4:Tube  
 Housing Material 5:HTN UL94V-0 Nature      Plating 1:Bright Plated Over Nickel 3:Gold Flash Over Nickel

PIN	DIM.A	DIM.B	PIN	DIM.A	DIM.B	PIN	DIM.A	DIM.B
02	2.00	8.00	07	12.00	18.00	12	22.00	28.00
03	4.00	10.00	08	14.00	20.00	13	24.00	30.00
04	6.00	12.00	09	16.00	22.00	14	26.00	32.00
05	8.00	14.00	10	18.00	24.00	15	28.00	34.00
06	10.00	16.00	11	20.00	26.00			



## 金上達科技股份有限公司

### GOLDENSUND TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ. 	TITLE: Wire To Board Wafer 2.00mm 90° SMT Single Row	
.x± 0.35	x.± 2'	APR. C.F.Liao 20140514	PART NO. AS06401XX5XX2	DWG NO. AS06401XX5XX2
.xx± 0.25	.x'± 1'	CHK. Abel 20140514	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15	.xx'± 0.5'	DRA. Michelle 20140514	SIZE: A4	SCALE 4:1
		SHEET 1 / 1		REV A0 V